

IN THE CLAIMS:

Please amend the claims as follows:

1. (Previously Presented) A multichip module structure, at least comprising:
 - a first multichip module substrate, comprising:
 - a semiconductor substrate having a first surface and a second surface;
 - an insulating layer on said first surface;
 - a multilayer interconnection structure on said insulating layer and having a third surface having a plurality of first bonding pads and a fourth surface having a plurality of second bonding pads on said insulating layer;
 - a plurality of conductive plugs penetrating said semiconductor substrate and said insulating layer and electrically connecting to said second bonding pads respectively;
 - a plurality of third bonding pads on said second surface and connecting to said conductive plugs respectively; and
 - a plurality of chips on said second surface and electrically connecting to said third bonding pads.
2. (Original) The multichip module structure according to claim 1, wherein said multilayer interconnection structure includes at least one integrated circuit device.
3. (Previously Presented) The multichip module structure according to claim 1, wherein said semiconductor substrate has a thickness between 10 to 500 micron.
4. (Original) The multichip module structure according to claim 1, wherein said chip is an active chip.
5. (Original) The multichip module structure according to claim 4, wherein said active chip is mounted on said second surface by flip-chip type.

6. (Original) The multichip module structure according to claim 1, wherein said chip is a passive chip.

7. (Original) The multichip module structure according to claim 1, wherein said chips individually and electrically connect to said third bonding pads.

8. (Previously Presented) The multichip module structure according to claim 1, wherein said plurality of chips comprise a first active chip mounted on said second surface by flip-chip type, and at least one chip electrically connecting and stacking on a backside of said first active chip.

9. (Original) The multichip module structure according to claim 8, wherein said at least one chip comprises a second active chip mounted on said backside of said first active chip by flip-chip type.

10. (Original) The multichip module structure according to claim 8, wherein said at least one chip comprises a passive chip.

11. (Original) The multichip module structure according to claim 1, further comprising a second multichip module substrate on said third surface, wherein said second multichip module substrate has a same structure as said first multichip module substrate.

12. (Previously Presented) The multichip module structure according to claim 1, wherein said multichip module structure is further electrically connected with a package substrate on said third surface.

Claims 13-24. (Canceled)